

		PAPER TITLE	AUTHOR	Company
Session ID / Paper	Time	Technical Sessions	Session Chair	Session Co-Chair
	AM	Counterfeit- Prevention & Mitigation Strategies		
A		Seminar Room	Aaron DerMardersosian aaron_dermardersosian_jr@raytheon.com	S. Ali Lilani Sultan.Lilani@integra-tech.com
1	8:30-8:55	An Update on the Authentication Platform DLA has Selected as Part of their Counterfeit Prevention Effort	Janice Meraglia	Applied DNA Sciences
2	8:55-9:20	Defense Electronic Trends	Tina Barclay	TAS Consulting
3	9:20-9:45	Counterfeit Analysis Supply Chain Case Studies - Counterfeit Detection & Quality Control Non Conformance Issues	Aaron DerMardersosian	Raytheon Company
	BREAK			
4	10:15-10:40	Ceramic Taggants for Authentication or Provenance Marking of Electronic Components	Dr. Arthur Jonath	Arthur Jonath Associates
5	10:40-11:05	Save Time and Money by Carefully Selecting Plastic Packaged Integrated Circuits	S. Ali Lilani	Integra Tech
	AM	RF and Microwave - Innovations and Emerging Technologies - Part I		
B		Colonial Room	Tom Terlizzi terlizzi@gmsystems.com	Larry Hawkins Larry.Hawkins@analog.com
1	8:30-8:55	The Current State of Integration in IC's	Larry Hawkins	Analog Devices Incorporated (ADI)
2	8:55-9:20	Packaging Technologies Behind GaN Power Transistors for High Power S-Band Radar Applications	Chris Hermanson	Cree, Inc.
3	9:20-9:45	High Temperature Cofired Ceramic (HTCC) Package Design and Applications	Ken McGillivray	HCC Electronic Packaging-(Aegis Ametek)
	BREAK			
4	10:15-10:40	Optimization of Tin Vapor Deposition Process on Tungsten-Copper Substrate	Dutta Sanchayan	Santier
5	10:40-11:05	High Reliability Designs and Manufacturing of RF Components and Assemblies	Chandra Gupta	Hittite Microwave
6	11:05-11:30	GaN Doherty Amplifiers for Commercial and Military Applications	Tom Kelly	NXP Semiconductors N.V.
	AM	Bumped Die Attach		
C		Cotillion Room	Jim McLenaghan ajm@creyr.net	Dan Baldwin dan.baldwin@engentaat.com
1	8:30-8:55	Next Generation Assembly Structures using Copper Wire Bonding Interconnection	Dr. Dan Baldwin	Engent, Inc.
2	8:55-9:20	Process Development for Ball Grid Array Attachment on DuPont™ Green Tape™ 9K7 LTCC	Allan Beikmohamadi	DuPont Microcircuit Materials
3	9:20-9:45	Thermo-Sonic Flip Chip Methods on Copper or Solder Interconnect Structures	Tae Yi	Panasonic Factory Solutions Co., LTD
	BREAK			
4	10:15-10:40	Reliability Issues in Flip Chip Design	Ed Dodd	DfR Solutions
5	10:40-11:05	Using Solid State Micro-Batteries in Flip-Chip Applications	Jeff Sather	Cymbet Corp
6	11:05-11:30	Selecting Stencil Technologies to Optimize Print Performance	Chrys Shea	Shea Engineering
	AM	NANO and MEMS		
D		Directors Room	Alan Rae arae@nanomic.org	Matt Apanius matt@smartmicrosystems.com
1	8:30-8:55	From Automotive Crash Sensing to Consumer Electronics and Beyond	Rob O'Reilly	MEMS Sensor and Technology Group, Analog Devices, Inc.
2	8:55-9:20	Advances in Thin, 3D and MEMS Die Bond Strength Testing	Bob Sykes	XYZTEC
3	9:20-9:45	Reliable Vacuum Packaging for MEMS: What Could Go Wrong	Igor Prikhodko	Analog Devices, Inc.
	BREAK			
4	10:15-10:40	Optical Leak Testing of MEMS Devices	Chris Aubertin	Norcom Systems Inc.
5	10:40-11:05	Alternative Miniature Vibration Sensor Technology	Dr. Atul Pradhan	Micatu, Inc.
Key Note Lunch Speaker				
		Restoring Vision with Subretinal Implants	Dr. Timo Lebold	Retina Implant AG

Session ID / Paper	Time	Technical Sessions	Session Chair	Session Co-Chair
	PM	Wire Bonding & Advanced Interconnections (Cu)	Bill Boyce wboyce@sensata.com	David DiPaola david@dceams.com
E		Seminar Room		
1	1:00-1:25	Design & Process Considerations to Avoid Resonance Induced Heel Cracks during an Ultrasonic Wire Bond Process	Jim Card	Sensata Technologies
2	1:25-1:50	Aluminum and Copper Wire Bonding to ENIG and ENEPIG	George Milad & Gerard O'Brien	Uyemura International Corporation
3	1:50-2:15	Configurations for Robust Gold Stitch-to-Substrate Wire Bond Attachment – Part 2	Ashley Hlavacik	Desich SMART Center
4	2:15-2:40	Heavy Copper Wedge Bonding in Power Electronics	Dr. Hans J. Hesse and Dr. Michael Broekelmann	Hesse Mechatronics, Inc.
5	2:40-3:05	Reworkable Interconnects using Alternative Materials	Dr Michael C. Hamilton	Auburn University
	PM	RF and Microwave - Innovations and Emerging Technologies - Part II	Tom Terlizzi terlizzi@gmsystems.com	Larry Hawkins Larry.Hawkins@analog.com
F1		Colonial Room		
1	1:00-1:25	Non-Hermetic Packaging of RF Microwave Modules	Matt Gruber	Lockheed Martin
2	1:25-1:50	A High Performance Single Component Conductive Epoxy for Inter-Connecting Silicon Stacked Die Layers - And a New Development for Globtop and Wirebond Protection for RF Devices	Samuel Forman	Microcoat Technologies
	PM	Novel Technologies	Dmitry Marchenko dmitry.marchenko@microsemi.com	
F2		Colonial Room		
3	1:50-2:15	Development of Low Temperature Sintered Nano Silver Pastes Using MO Technology and Resin Reinforcing Technology	Ken Aruajo	NAMICS Technologies
4	2:15-2:40	Design and Fabrication of a Highly Integrated Silicon Detector for the STAR Experiment at Brookhaven National Laboratories	Benjamin Buck	MIT/Brookhaven Laboratories
5	2:40-3:05	Boston Retinal Implant Group	Doug Shire	Boston Retinal Group
	PM	Technologies and Methods for 2.5/3D Packaging	Ken Aruajo aruajo@namics-usa.com	Maria Durham mdurham@indium.com
G		Cotillion Room		
1	1:00-1:25	Pre-Applied Materials for 2.5/3D Technology	Ken Aruajo	NAMICS Technologies
2	1:25-1:50	Progress in Fabrication and Test of Glass Interposer Substrates	Aric Shorey	Corning, Inc.
3	1:50-2:15	Comparison of Measured and Modeled Lithographic Process Capabilities for 2.5D and 3D Applications Using a Step and Repeat Camera	James Webb	Rudolph Technologies, Inc.
4	2:15-2:40	Recent Advances in Die Attach Film and Temporary Wafer Protection	Frederick Lo, Maurice Leblon and Kevin Chung	AI Technology Inc
5	2:40-3:05	Evaluating Underfill Material for 3D Integration of High Density Heterogeneous Sensor Arrays	Chris Gregory	RTI International
	All Day	Poster Session	Dr. Wei Han weihan.vivian@gmail.com	Dr. Rita Mohanty ritam1010@hotmail.com
H		Federal Room / Registration Area		
1		The Effect of Current Density on the Grain Size and Surface Morphology of Electrodeposited Pt Nanowires	Dajiang Ruan, Fan Gao and Zhiyong Gu	Department of Chemical Engineering University of Massachusetts Lowell
2		Low Temperature Soldering Using Tin/Indium (Sn/In) Lead-free Nanosolders	Yang Shu, Edward S. Fratto, Zhiyong Gu	Department of Chemical Engineering University of Massachusetts Lowell
3		Microfluidic Synthesis of Lead-free Nanosolder Particles	Zhiyang Li, Yang Shu, Zhiyong Gu	Department of Chemical Engineering University of Massachusetts Lowell
4		PCA Environmental Compliance and Verification Tools	Scott Mazur	Benchmark Electronics-NH
5		Hydrogen for Small Scale Semiconductor Fabrication and Packaging	Dave Wolff	Proton On Site
6		Criteria for Selecting a Solder Paste and Troubleshooting Common Challenges	Derrick Herron	Indium Corporation, NY